









PRODUCT DATASHEET



- ► Subminiature SMD
- ➤ 2520 Series
- ➤ Yellow (595nm)

N0Y08S21









Release Date: 13 November 2015 Version: A1.0



Subminiature 2520

APPLICATIONS:

- Backlighting
- Indication Light
- Switch light
- Dashboard

FEATURES:

Package: Subminiature SMD Forward Current: 20mA

Forward Voltage (typ.): 2.2V

Luminous Intensity (typ.): 900mcd @20mA

Colour: Yellow Wavelength: 595nm

Viewing angle: 20°

Materials:

Die: AlGaInP

Resin: Epoxy (Water Clear) Operating Temperature: -40~+85°C

Storage Temperature: -40~+100°C

ESD: 2000V

Grouping parameters:

Forward voltage

Luminous intensity

Dominant Wavelength

Soldering methods: Reflow

Preconditioning: acc. to JEDEC Level 3

Packing: 12mm tape with 1500/reel, ø180mm (7")



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	50	mA
Peak Forward Current Duty 1/10@10KHz	I _{FP}	90	mA
Reverse Current @5V	I _R	10	μΑ
Power Dissipation	PD	120	mW
Electrostatic Discharge	ESD	2000	V
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+100	°C

Electrical & Optical Characteristics (Ta=25°C)

Darameter	Symbol	Values		Unit	Test	
Parameter	Зуппон	Min.	Тур.	Max.	Offic	Condition
Forward Voltage	V_{F}	1.7		2.6	V	I _F =20mA
Luminous Intensity	I _V	550	900		mcd	I _F =20mA
Dominant Wavelength	λ_{D}		595		nm	I _F =20mA
Spectral Line Half Bandwidth	Δλ		15		nm	I _F =20mA
Viewing Angle	2θ _{1/2}		20		deg	I _F =20mA

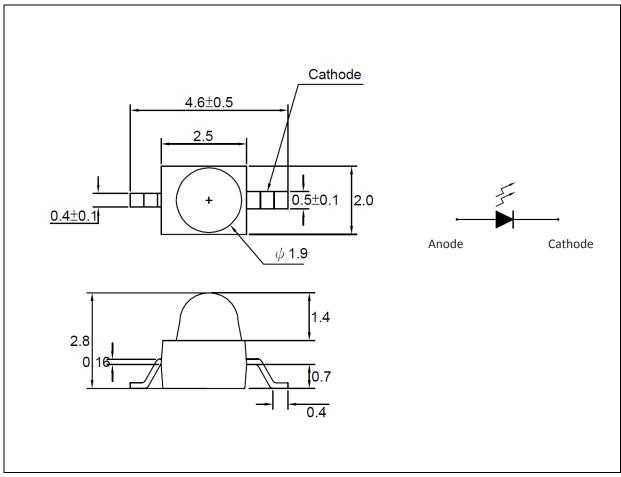
^{1.} Luminous intensity (I_V) ±15%, Forward Voltage (V_F) ±0.1V, Viewing angle(2 $\theta_{1/2}$) ±5%

^{2.} IS standard testing



OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.



BINNING GROUPS:

Forward Voltage Classifications ($I_F = 20mA$):

Code	Min.	Max.	Unit
1	1.7	1.8	
2	1.8	1.9	
3	1.9	2.0	
4	2.0	2.1	
5	2.1	2.2	V
6	2.2	2.3	
7	2.3	2.4	
8	2.4	2.5	
9	2.5	2.6	

Luminous Intensity Classifications (I_F = 20mA):

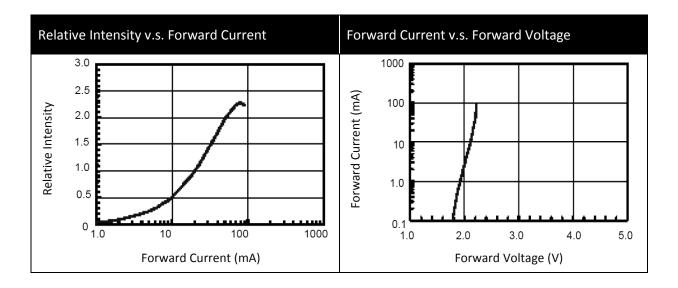
Code	Min.	Max.	Unit
YC1	550	600	
YC2	600	700	
YC3	700	800	
YC4	800	900	med
YC5	900	1000	mcd
YC6	1000	1100	
YC7	1100	1200	
YC8	1200	1300	

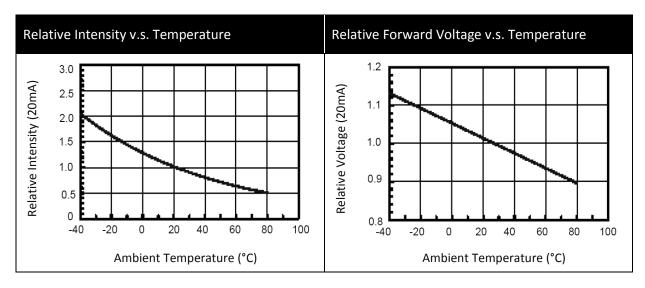
Dominant Wavelength Classifications (I_F = 20mA):

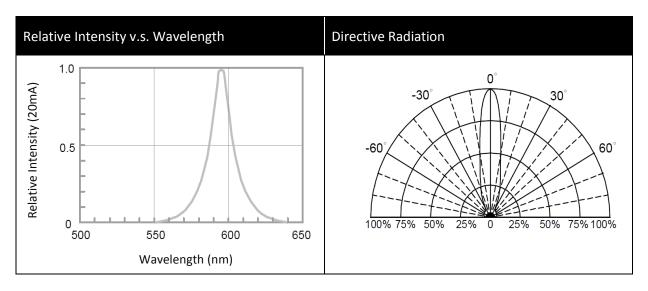
Code	Min.	Max.	Unit
32	590	595	2.22
33	595	600	nm



ELECTRO-OPTICAL CHARACTERISTICS:



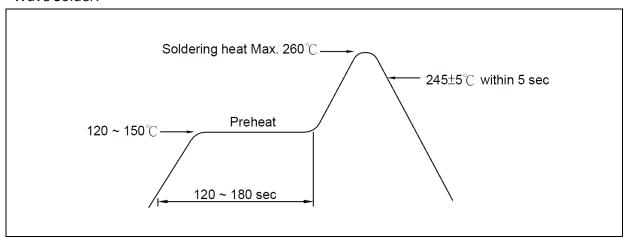




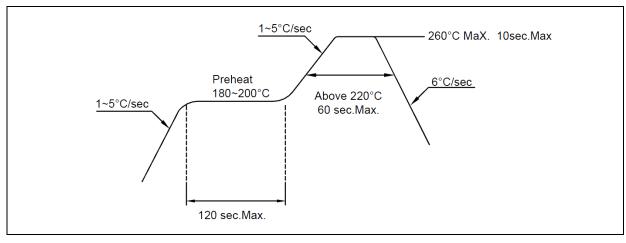


RECOMMENDED SOLDERING PROFILE:

Wave Solder:



Lead-free Solder:



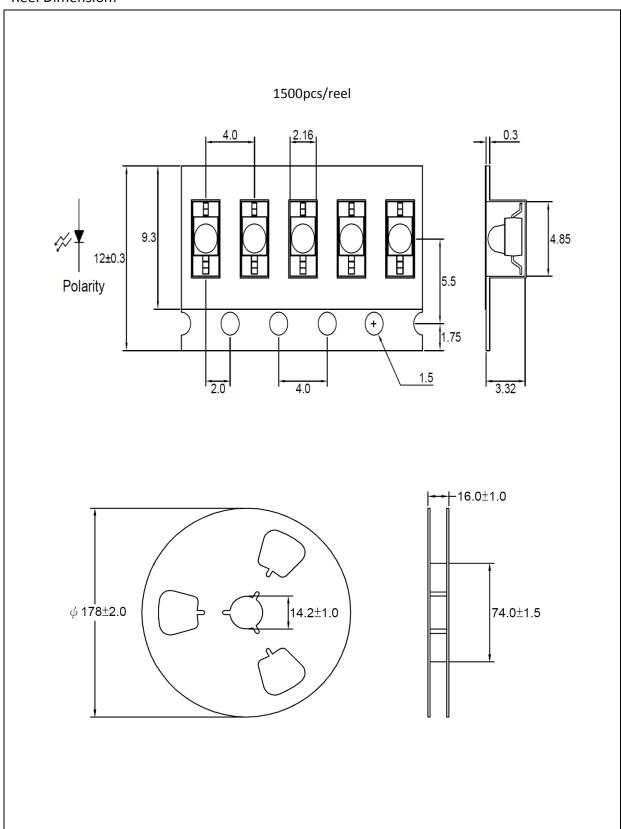
Note:

- 1. Maximum reflow soldering: 2 times.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

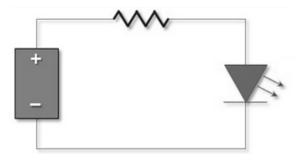
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	15/04/2014	Datasheet set-up.
A1.1	13/11/2015	Part number change.